



04-24-2002



102065969

Docket No.: XA-9629

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

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To the Honorable Commissioner of Patents and Trademarks, Patent and Trademark Office, Washington, D.C. 20503
Please attach original documents or copy thereof.

1. Name of conveying party(ies):

Yutaka SHIMADA
Yasuhiro MORI
Koyo MORITA
Kenji YOKOSHIMA

4.18.02

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: Hitachi, Ltd.

Address: 6, Kanda Surugadai 4-chome

Chiyoda-ku

City: Tokyo

State/Prov.:

Country: Japan

ZIP:

Additional name(s) & address(es)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

Execution Date: April 4, 2002

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is:

Patent Application No.

Filing date

B. Patent No.(s)

10/083,402

February 27, 2002

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mitchell W. Shapiro

Registration No. 31,568

Address: Miles & Stockbridge P.C.

1751 Pinnacle Drive

04/19/2002 CNGUYEN 00000060 10083402

02 EC:581

Suite 500

40.00 DP

City: McLean

State/Prov.: VA

Country: US

ZIP: 22102-3833

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41): \$ 40.00

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account

☐ Authorized to be charged to deposit account

8. Deposit account number:

50-1165

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Mitchell W. Shapiro

Name of Person Signing

Signature

April 18, 2002

Date

Total number of pages including cover sheet, attachments, and

2

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments

PATENT
REEL: 012806 FRAME: 0642

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

MANUFACTURING METHOD OF SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) Yutaka Shimada

4/4/2002

2) Yasuhiko Mori

4/4/2002

3) Koyo Morita

4/4/2002

4) Kenji Yokoshima

4/4/2002

5) _____

6) _____

7) _____

8) _____

9) _____

10) _____

RECORDED: 04/18/2002

PATENT
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